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公司 (SHANGHAI PATENT & TRADEMARK LAW

(54) 发明名称: 电镀装置

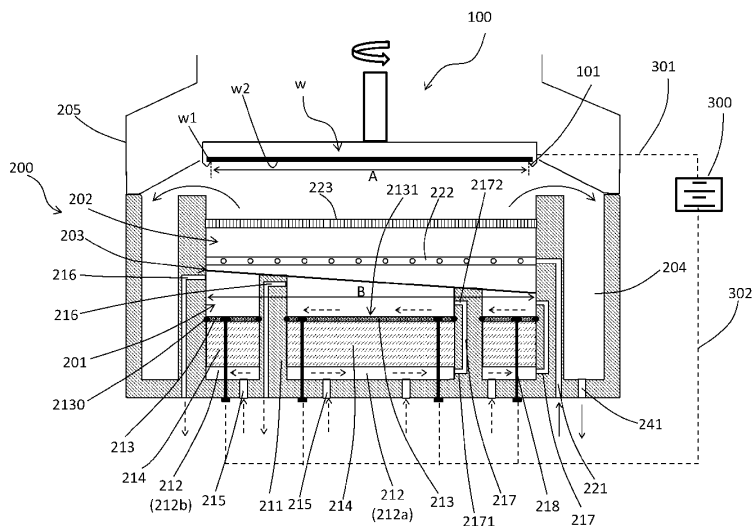


图 1

(57) **Abstract:** Provided in the present invention is an electroplating device. A solid anode, a meshed anode or a perforated anode is arranged in an anode area to serve as an inert anode, and a constant distance is maintained between the inert anode and a substrate, so as to form a stable electric field on the surface of the substrate, thereby improving the electroplating uniformity; an active anode is arranged below the inert anode in the anode area for continuously supplementing metal ions during an electroplating process, such that the metal ions are more sufficiently transmitted to the substrate, thereby achieving the effect of improving the electroplating uniformity; and parts, such as a rectifying plate, a fluid dispersion pipe or a stirring portion, are arranged in the anode area, such that an anode liquid

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is uniformly dispersed, thereby further improving the electroplating uniformity.

(57) 摘要: 本发明提出的电镀装置, 通过在阳极区设置实心阳极、网状阳极或者穿孔阳极作为惰性阳极, 与基板之间保持恒定距离, 以在基板表面形成稳定的电场, 从而改善电镀的均匀性; 通过在阳极区的惰性阳极下方设置活性阳极, 用以在电镀过程中不断补充金属离子, 以使金属离子更充足地传输至基板, 从而起到改善电镀均匀性的作用; 通过在阳极区设置整流板、流体分散管或者搅拌部等部件, 用以使阳极液均匀分散, 进一步改善电镀的均匀性。